

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.80mil	SM-005	Solder Mask	GTS
CF-007	Top Layer	1.60mil	1/2 oz	Signal	GTL
Prepreg		4.48mil	FR408(HR)	Dielectric	
CF-008	Ground Layer 2	1.20mil	1/2 oz	Signal	G1
Core		4.00mil	FR408(HR)	Dielectric	
CF-008	Signal Layer 3	1.20mil	1/2 oz	Signal	G2
Prepreg		4.36mil	FR408(HR)	Dielectric	
CF-008	Signal Layer 4	1.20mil	1/2 oz	Signal	G3
Core		4.00mil	FR408(HR)	Dielectric	
CF-008	Ground Layer 5	1.20mil	1/2 oz	Signal	G4
Prepreg		4.36mil	FR408(HR)	Dielectric	
CF-008	Power Layer 6	1.20mil	1/2 oz	Signal	G5
Core		4.00mil	FR408(HR)	Dielectric	
CF-008	Ground Layer 7	1.20mil	1/2 oz	Signal	G6
Prepreg		4.36mil	FR408(HR)	Dielectric	
CF-008	Ground Layer 8	1.20mil	1/2 oz	Signal	G7
Core		4.00mil	FR408(HR)	Dielectric	
CF-008	Power Layer 9	1.20mil	1/2 oz	Signal	G8
Prepreg		4.36mil	FR408(HR)	Dielectric	
CF-008	Power Layer 10	1.20mil	1/2 oz	Signal	G9
Core		4.00mil	FR408(HR)	Dielectric	
CF-008	Ground Layer 11	1.20mil	1/2 oz	Signal	G10
Prepreg		4.48mil	FR408(HR)	Dielectric	
CF-007	Bottom Layer	1.60mil	1/2 oz	Signal	GBL
Surface Material	Bottom Solder	0.80mil	SM-005	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 63.20mil

DRS4-PCB.PCBDwf

Drawn by: Sean Quinn

Size: A3

Revision: 73f2467b

Date: 3/30/2021

Time: 1:27 PM

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File: DRS4-PCB.PCBDwf

GAPS TOF
475 Portola Plaza
Los Angeles, CA
310-825-0344

igarcia91@g.ucla.edu
andrew.peck@cern.ch
spq@ucla.edu

